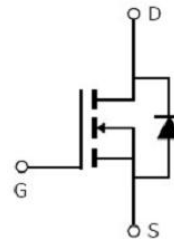


V_{DSS}	60V
$R_{DS(on)}$	9m (typ.)
I_D	55A



Advanced MOSFET process technology
 Special designed for PWM, load switching and
 general purpose applications
 Ultra low on-resistance with low gate charge
 Fast switching and reverse body recovery
 150 operating temperature



It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	55	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	36	
I_{DM}	Pulsed Drain Current	220	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	83	W
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-to-Source Voltage	± 20	V
$T_J \quad T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$



R_{JC}	Junction-to-case	—	1.5	/W

@ $T_J=25$ unless otherwise specified

$V_{(BR)DSS}$ Drain-to-Source breakdown voltage 60 — — V $V_{GS} = 0V$

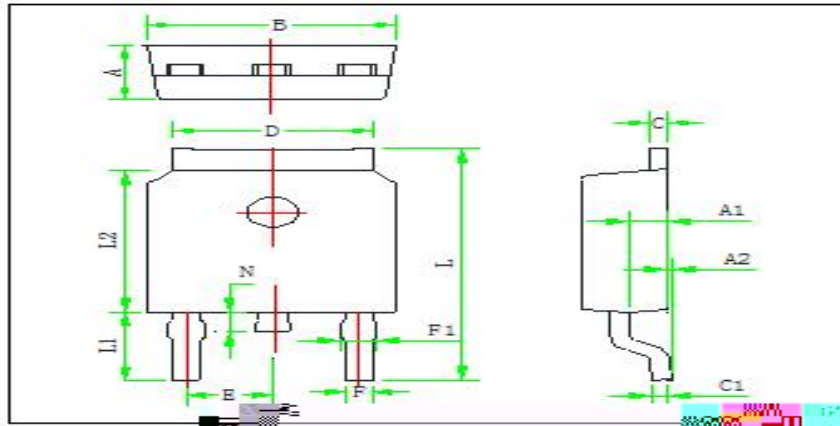
EXTRA



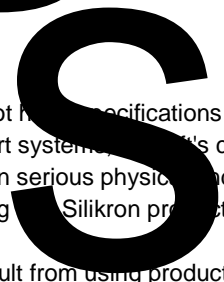
Calculated continuous current based on maximum allowable junction temperature.

Repetitive ~~current~~ limited by max. junction temperature.

The



Symbol	0.5	1.0	1.5
A	0.66	0.76	0.86
A1	0.66	0.86	1.06
A2	0.66	0.86	1.06
B	5.12	5.32	5.52
C	0.43	0.50	0.58
C1	0.43	0.50	0.58
D	5.12	5.32	5.52
E	2.286 TYP		
F	0.66	0.76	0.86
F1	0.66	0.86	1.06
L	9.60	9.90	10.20
L1	2.6	2.8	3.0
L2	5.95	6.10	6.25
N	0.60	0.80	1.00



Any and all Silikron products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, medical control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your Silikron representative nearest you before using any Silikron products described or contained herein in such applications.

Silikron assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Silikron products described or contained herein.

Specifications of any and all Silikron products described or contained herein stipulate the performance, characteristics, and functions

characteristics

silikron products do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, medical control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage.

of

consult with your silikron representative nearest you before using any silikron products described or contained herein in such applications.

silikron assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all silikron products described or contained herein.

